

In the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended). An electronic circuit unit comprising:
 - an alumina substrate;
 - thin film circuit elements including capacitors, resistors, and inductance elements formed on the alumina substrate;
 - thin film conducting patterns connected to the circuit elements formed on the alumina substrate; and
 - a semiconductor bare chip mounted on the alumina substrate and wire bonded to the conducting pattern~~[[,]]~~; and
a ground conducting pattern formed on and at least partially covering the alumina substrate,wherein at least one of the capacitors is comprised of a portion of the ground conducting pattern, a dielectric layer above at least the portion of the ground conducting pattern, and an upper plate above at least a portion of the dielectric layer, the upper plate having a ~~is comprised of two parallel plates disposed on either side of a dielectric material and whose perimeter of~~ [[has]] a non-rectangular shape.
2. (Cancelled)
3. (Previously presented) The electronic circuit unit according to claim 1, wherein the non-rectangular capacitor is a ground capacitor.
4. (Cancelled)
5. (Previously presented) An electronic circuit unit comprising thin film circuit elements including conducting patterns formed on an alumina substrate, a plurality of thin film capacitors formed on the alumina substrate so as to be connected to the

conducting patterns, resistors, and inductance elements and a semiconductor bare chip having a transistor wire-bonded to the conducting patterns, wherein the conducting pattern has a connection land connected to an electrode of the transistor to be grounded in a high frequency band, the capacitor has a plurality of ground capacitors grounded in the high frequency band, and one electrode of each of the plurality of capacitors is connected to the ground conducting pattern and the other electrode of each of the plurality of capacitors is connected to the connection land through the conducting patterns that are separated from each other.

6. (Original) The electronic circuit unit according to claim 5, wherein the plurality of ground capacitors are different from each other in size.

7. (Previously presented) The electronic circuit unit according to claim 5, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

8. (Previously presented) The electronic circuit unit according to claim 6, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

9. (Previously presented) The electronic circuit unit according to claim 3, wherein a portion of the thin film conducting pattern formed on the substrate and disposed on one side of the dielectric material serves as the one electrode of a ground capacitor.

10. (Previously presented) The electronic circuit as in claim 1, wherein each ~~parallel plate~~ the upper plate of the non-rectangular capacitor is comprised of a plurality of contiguous rectangular areas, at least one of which has different linear dimensions or orientation.

11. (Previously presented) The electronic circuit unit according to claim 10, wherein the non-rectangular capacitor is a ground capacitor.

12. (New) The electronic circuit according to claim 1, wherein the upper conductive plate is a polygon, the sum of whose interior angles is greater than 360 degrees.

13. (New) An electronic circuit unit comprising:

- an alumina substrate;
- thin film circuit elements including capacitors, resistors, and inductance elements formed on the alumina substrate;
- thin film conducting patterns connected to the circuit elements formed on the alumina substrate;
- a semiconductor bare chip mounted on the alumina substrate and wire bonded to the conducting pattern; and
- a ground conducting pattern formed on and at least partially covering the alumina substrate,

wherein at least one of the capacitors is comprised of an upper electrode disposed on a facing surface of a dielectric material, and the upper electrode is formed in the shape in which comprises a first rectangle and at least a second rectangle, which projects therefrom to create a polygon with greater than four sides.